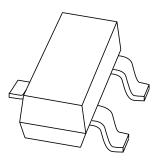
# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **BCW60 series**NPN general purpose transistors

Product data sheet Supersedes data of 1997 Mar 10 1999 Apr 22



# **NPN** general purpose transistors

## **BCW60** series

#### **FEATURES**

• Low current (max. 100 mA)

• Low voltage (max. 32 V).

#### **APPLICATIONS**

• General purpose switching and amplification.

#### **DESCRIPTION**

NPN transistor in a SOT23 plastic package. PNP complements: BCW61 series.

#### **MARKING**

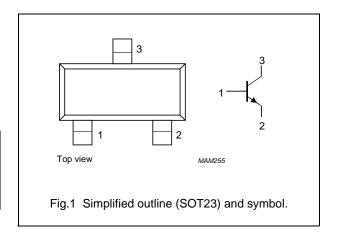
TYPE NUMBER	MARKING CODE(1)
BCW60B	AB*
BCW60C	AC*
BCW60D	AD*

#### Note

\* = p : Made in Hong Kong.
 \* = t : Made in Malaysia.

#### **PINNING**

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	32	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	32	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	5	V
Ic	collector current (DC)		_	100	mA
I <sub>CM</sub>	peak collector current		_	200	mA
I <sub>BM</sub>	peak base current		-	200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

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# NPN general purpose transistors

BCW60 series

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W	

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 32 V	_	_	20	nA
		I <sub>E</sub> = 0; V <sub>CB</sub> = 32 V; T <sub>amb</sub> = 150 °C	_	_	20	μΑ
I <sub>EBO</sub>	emitter cut-off current	I <sub>C</sub> = 0; V <sub>EB</sub> = 4 V	_	_	20	nA
h <sub>FE</sub>	DC current gain	$I_C = 10 \mu A; V_{CE} = 5 V$				
	BCW60B		20	_	_	
	BCW60C		40	_	_	
	BCW60D		100	_	_	
	DC current gain	I <sub>C</sub> = 2 mA; V <sub>CE</sub> = 5 V				
	BCW60B		180	_	310	
	BCW60C		250	_	460	
	BCW60D		380	_	630	
	DC current gain	I <sub>C</sub> = 50 mA; V <sub>CE</sub> = 1 V				
	BCW60B		70	_	_	
	BCW60C		90	_	_	
	BCW60D		100	_	_	
V <sub>CEsat</sub>	collector-emitter saturation	$I_C = 10 \text{ mA}; I_B = 0.25 \text{ mA}$	50	_	350	mV
	voltage	I <sub>C</sub> = 50 mA; I <sub>B</sub> = 1.25 mA	100	_	550	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 10 mA; I <sub>B</sub> = 0.25 mA	600	_	850	mV
		I <sub>C</sub> = 50 mA; I <sub>B</sub> = 1.25 mA	0.7	_	1.05	V
$V_{BE}$	base-emitter voltage	I <sub>C</sub> = 10 μA; V <sub>CE</sub> = 5 V	_	520	_	mV
		I <sub>C</sub> = 2 mA; V <sub>CE</sub> = 5 V	550	650	750	mV
		I <sub>C</sub> = 50 mA; V <sub>CE</sub> = 1 V	_	780	_	mV
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = 10 \text{ V}$ ; $f = 1 \text{ MHz}$	_	1.7	_	pF
C <sub>e</sub>	emitter capacitance	$I_C = I_C = 0$ ; $V_{EB} = 0.5 \text{ V}$ ; $f = 1 \text{ MHz}$	_	11	_	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 10 mA; V <sub>CE</sub> = 5 V; f = 100 MHz; note 1	100	250	_	MHz
F	noise figure	$I_C = 200 \mu A; V_{CE} = 5 V;$ $R_S = 2 k\Omega; f = 1 kHz; B = 200 Hz$	_	2	6	dB

3

### Note

1. Pulse test:  $t_p \leq 300~\mu s;~\delta \leq 0.02.$ 

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# NPN general purpose transistors

BCW60 series

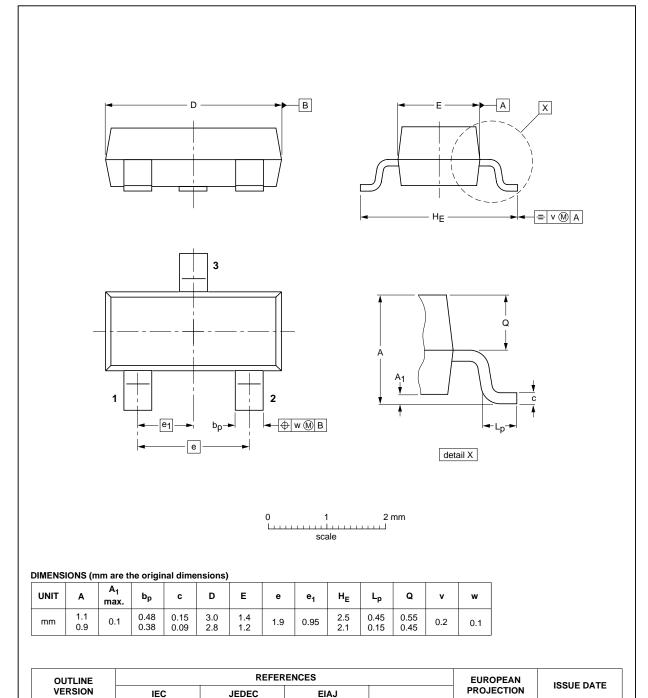
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99-09-13

#### **PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

SOT23



TO-236AB

SOT23

# **NPN** general purpose transistors

#### **BCW60** series

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

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